

Silicon Diode

BYW29-150

Fast Efficient Rectifier

150V / 8A

DATASHEET

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OEM – General Semiconductor

Source: General Semiconductor Databook 1998

BYW29-50 THRU BYW29-200

FAST EFFICIENT PLASTIC RECTIFIER

Reverse Voltage - 50 to 200 Volts Forward Current - 8.0 Amperes

FEATURES

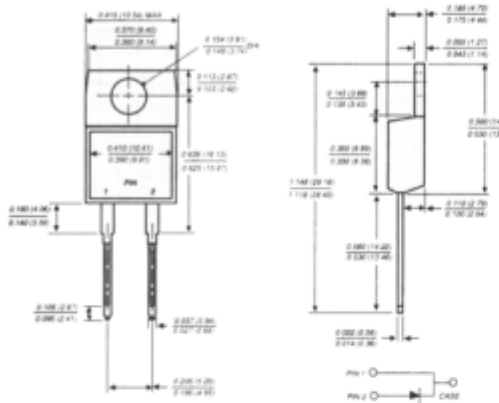
- ◆ Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- ◆ Glass passivated chip junction
- ◆ Low power loss
- ◆ Low leakage current
- ◆ High surge current capability
- ◆ Superfast recovery time for high efficiency
- ◆ High temperature soldering guaranteed: 250°C, 0.16" (4.06mm) from case for 10 seconds



MECHANICAL DATA

Case: JEDEC TO-220AC molded plastic body over passivated chip
Terminals: Plated lead solderable per MIL-STD-750, Method 2026
Polarity: As marked
Mounting Position: Any
Weight: 0.064 ounce, 1.81 grams

TO-220AC



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

	SYMBOLS	BYW29-50	BYW29-100	BYW29-150	BYW29-200	UNITS
Maximum repetitive peak reverse voltage	VRRM	50	100	150	200	Volts
Maximum RMS voltage	VRMS	35	70	105	140	Volts
Maximum DC blocking voltage	VDC	50	100	150	200	Volts
Maximum average forward rectified current at TC=125°C	IAV	8.0				Amps
Peak forward surge current 10ms single half sine-wave superimposed at TJ=150°C	IFSM	100.0				Amps
Maximum instantaneous forward voltage at: IF=20A, TJ=25°C IF=8A, TJ=150°C	VF	1.3 0.8				Volts
Maximum DC reverse current at rated DC blocking voltage TC=25°C TC=100°C	IR	10.0 500.0				µA
Maximum reverse recovery time (NOTE 1)	trr	25.0				ns
Typical junction capacitance (NOTE 2)	CJ	45.0				pF
Maximum thermal resistance (NOTE 3) (NOTE 4)	ReJA ReJC	20.0 3.0				°C/W
Operating and storage temperature range	TJ, TSTG	-65 to +150				°C

NOTES:

- (1) Reverse recovery test conditions: IF=1A, VR=30V, di/dt=100A/µs, I_r=10%, I_{AV} for measurement of t_r
- (2) Measured at 1.0 MHz and applied reverse voltage of 4.0 Volts
- (3) Thermal resistance from junction to ambient in free air; no heatsink
- (4) Thermal resistance from junction to case mounted on heatsink

RATINGS AND CHARACTERISTIC CURVES BYW29-50 THRU BYW29-200

FIG. 1 - MAXIMUM FORWARD CURRENT DERATING CURVE

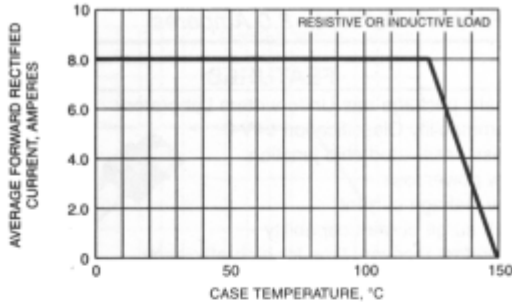


FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

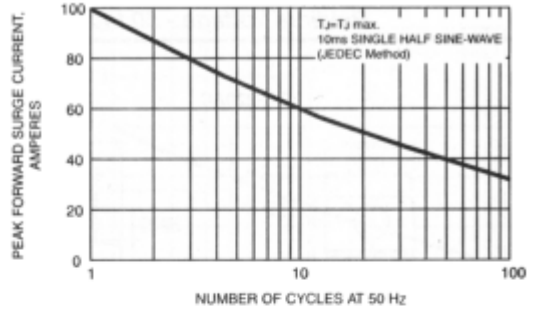


FIG. 3 - TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

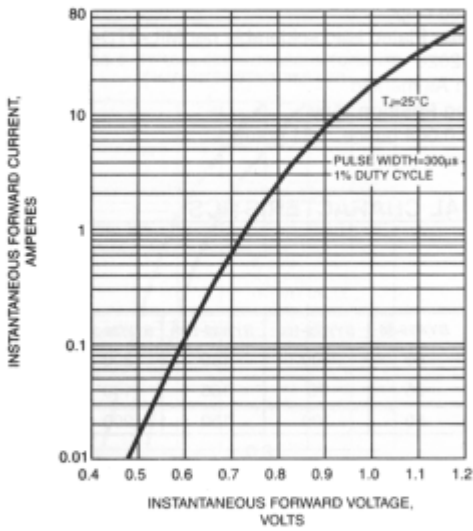


FIG. 4 - TYPICAL REVERSE LEAKAGE CHARACTERISTICS

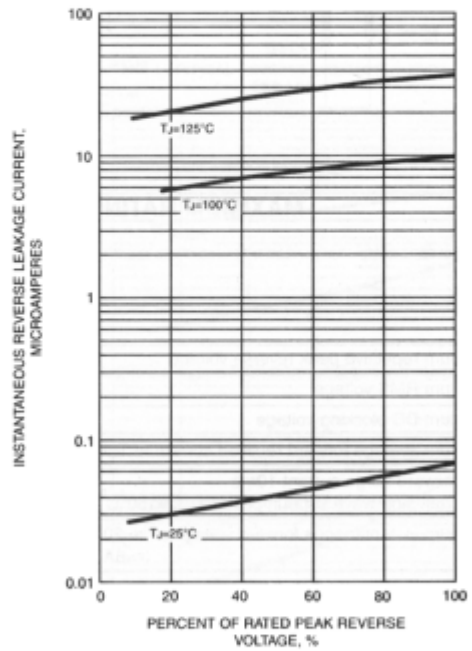


FIG. 5 - TYPICAL JUNCTION CAPACITANCE

